REMARKS/ARGUMENTS

Claims 1-20 are pending in this application. By the amendment, Applicants amend claims 1 and 11.

Claims 1, 2, and 5 were rejected under 35 U.S.C. § 102(b) as being clearly anticipated by Morimoto (JP 08-241900). Claims 11, 12, and 15 were rejected under 35 U.S.C. § 102(b) as being clearly anticipated by Morimoto. Claims 1, 2, 5, and 7 were rejected under 35 U.S.C. § 102(b) as being clearly anticipated by Wille et al. (U.S. 5,821,456). Claims 4, 6-10, 14, and 16-20 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Morimoto. Claims 3, 4, 6, and 8-10 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Wille et al. Claims 11-20 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Wille et al., and further in view of Morimoto.

Claim 1 has been amended to recite:

> "A method for fabricating a circuit module comprising the steps of:
> **supplying a resin from a dispenser needle disposed at a supplying position** onto a substrate on which a chip component is mounted in a flip chip configuration so as **to form a resin pool between a sidewall of the chip component and a sidewall of the dispenser needle**; and
> **filling substantially an entire gap between the chip component and the substrate with the resin of the resin pool while the dispenser needle is disposed at the supplying position.**"
> (emphasis added)

Claim 11 recites method steps and features that are similar to the method steps and features recited in claim 1, including the above-emphasized method steps.

The Examiner alleged that each of Morimoto and Wille et al. teaches all of the method steps and features recited in Applicants' claim 1, and that Morimoto teaches all of the method steps and features recited in Applicants' claim 11. Applicants respectfully disagree.

Claim 1 has been amended to recite the method steps of "supplying a resin from a dispenser needle disposed at a supplying position ... to form a resin pool between a sidewall of the chip component and a sidewall of the dispenser needle" and "filling substantially an entire gap between the chip component and the substrate with the resin of the resin pool while the dispenser needle is disposed at the supplying position." Claim 11 has been similarly amended.

In the Response to Arguments section on page 2 of the outstanding Office Action, the Examiner alleged that "Figures 1(b) and 2(b) [of Morimoto] both teach forming a resin pool [6]. The pool clearly forms to at least the bottom of the dispenser. It is the examiner's position that the resin inherently would rise up the sidewall of the dispenser through capillary action. Further figure 2(b) clearly shows the resin pool as pooling up the needle wall." Applicants respectfully disagree.

First, contrary to the Examiner's allegations, the bottom of the dispenser 5 of Morimoto is **spaced above and away from** the resin 6, as clearly seen in Figs. 1(b) and 2(b) of Morimoto. The narrow portion between the dispenser 5 and the resin 6 is a stream of resin that is dispensed from an opening in the bottom surface of the dispenser 5. The only way that the resin 6 of Morimoto could rise up the sidewall of the dispenser 5 through capillary action would be if the bottom of the dispenser 5 was in contact with the pool of resin 6. Since the bottom of the dispenser 5 of Morimoto is spaced above and away from the pool of resin 6, no capillary action occurs or is possible, and thus, no resin would rise up the sidewall of the dispenser 5.

Thus, contrary to the Examiner's allegation, Morimoto clearly fails to teach or suggest the method step of "supplying a resin from a dispenser needle disposed at a supplying position ... to form a resin pool between a sidewall of the chip component and a sidewall of the dispenser needle" as recited in Applicants' claim 1, and similarly in Applicants' claim 11.

Second, as clearly seen in Figs. 1(c), 1(d), 2(c) and 2(d) of Morimoto, the dispenser is moved away from the supplying position **before** the resin is filled into the

gap between the chip component 1 and the substrate 3. Thus, Morimoto certainly fails to teach or suggest the method step of "filling substantially an entire gap between the chip component and the substrate with the resin of the resin pool while the dispenser needle is disposed at the supplying position" as recited in Applicants' claim 1, and similarly in Applicants' claim 11.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of claims 1 and 11 under 35 U.S.C. § 102(b) as being clearly anticipated by Morimoto.

Wille et al. fails to teach or suggest any specific arrangement of a dispenser needle with respect to the chip component 14 or the pool of resin 26. In fact, Wille et al. fails to teach or suggest anything at all about how the resin 26 is supplied to the location shown in Fig. 1 of Wille et al. Thus, Wille et al. certainly fails to teach or suggest the method steps of "supplying a resin from a dispenser needle disposed at a supplying position to form a resin pool between a sidewall of the chip component and a sidewall of the dispenser needle" and "filling substantially an entire gap between the chip component and the substrate with the resin of the resin pool while the dispenser needle is disposed at the supplying position" as recited in Applicants' claim 1, and similarly in Applicants' claim 11.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of claim 1 under 35 U.S.C. § 102(b) as being clearly anticipated by Wille et al.

Since neither Wille et al. nor Morimoto teaches or suggests the features of "supplying a resin from a dispenser needle disposed at a supplying position ... to form a resin pool between a sidewall of the chip component and a sidewall of the dispenser needle" and "filling substantially an entire gap between the chip component and the substrate with the resin of the resin pool while the dispenser needle is disposed at the supplying position" as recited in Applicants' claim 11, the combination of Morimoto and Wille et al. clearly fails to render Applicants' claim 11 obvious.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of claim 11 under 35 U.S.C. § 103(a) as being unpatentable over Wille et al. in view of Morimoto.

Accordingly, Applicants respectfully submit that Morimoto and Wille et al., applied alone or in combination, fail to teach or suggest the unique combination of features and method steps recited in Applicants' claims 1 and 11.

In view of the foregoing remarks, Applicants respectfully submit that claims 1 and 11 are allowable. Claims 2-10 and 12-20 are dependent upon claims 1 and 11, and are therefore allowable for at least the reasons that claims 1 and 11 are allowable.

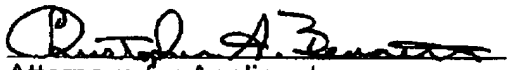
In view of the foregoing remarks, Applicants respectfully submit that this application is in condition for allowance. Favorable consideration and prompt allowance are solicited.

To the extend necessary, Applicants petition the Commissioner for a One-month extension of time, extending to December 22, 2005, the period for response to the Office Action dated August 22, 2005.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

Date: December 13, 2005



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